

This diagram shows a detailed cross-section of the device 100. It features a central vertical assembly with various layers and components labeled with reference numerals. At the top, a curved element 10 is shown. Below it, a series of layers are depicted, including a conductive layer 4, a dielectric layer 12, and a substrate 27. The central core consists of several stacked layers: 18, 20, 21, 22, and 23, which are collectively labeled as 14. These layers are separated by thin insulating layers 8 and 23. A central vertical channel or cavity is formed, containing elements 5 and 6. On the left side, there are circular openings 13a and 13. The bottom of the device shows a base layer 26 and a contact pad 31. Electrical connections are indicated by wavy lines representing wires or leads. A small inset at the bottom right provides a magnified view of the interface between the base layer 26 and the contact pad 31, showing the underlying structure 29 and the connection point 25.

Fig. 2A

Fig. 2B

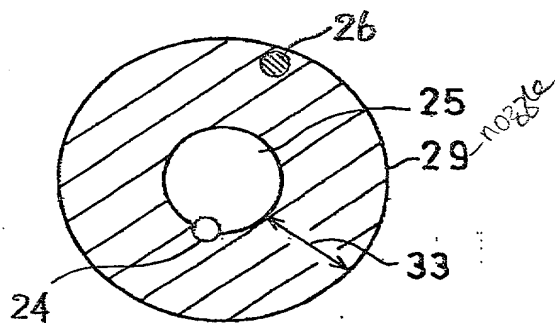


Fig. 4A

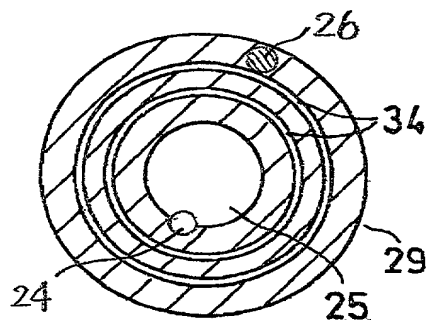


Fig. 4B

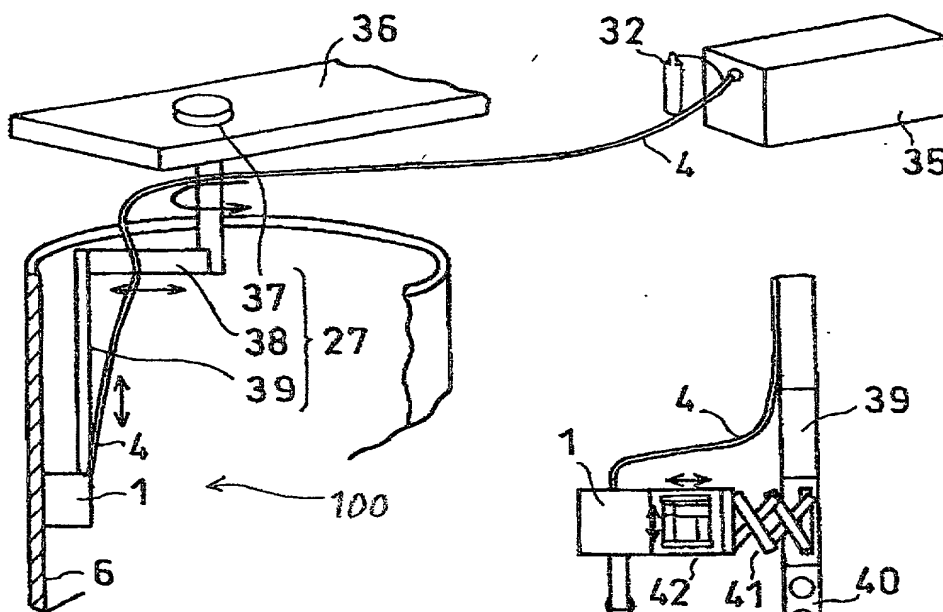


Fig. 3A

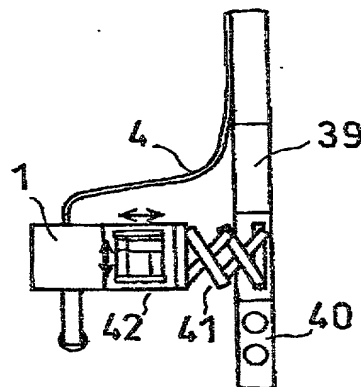


Fig. 3B

LASER OSCILLATOR	WAVELENGTH	OUTPUT POWER	PROCESS SPEED	WELDING WIRE	WIRE FEEDING SPEED
YAG LASER	1.06 μm	0.5~ 4.0 kW	0.1~5 m/min	ϕ 0.4~ 1.0 mm	0.5~8 m/min

Fig. 5

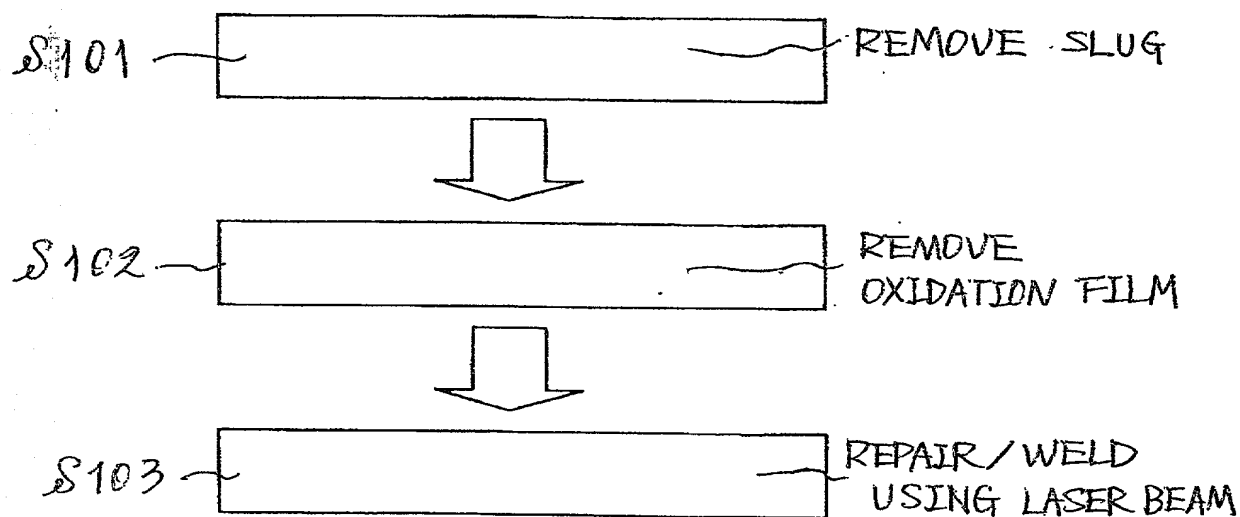


Fig. 6

FIG. 7B

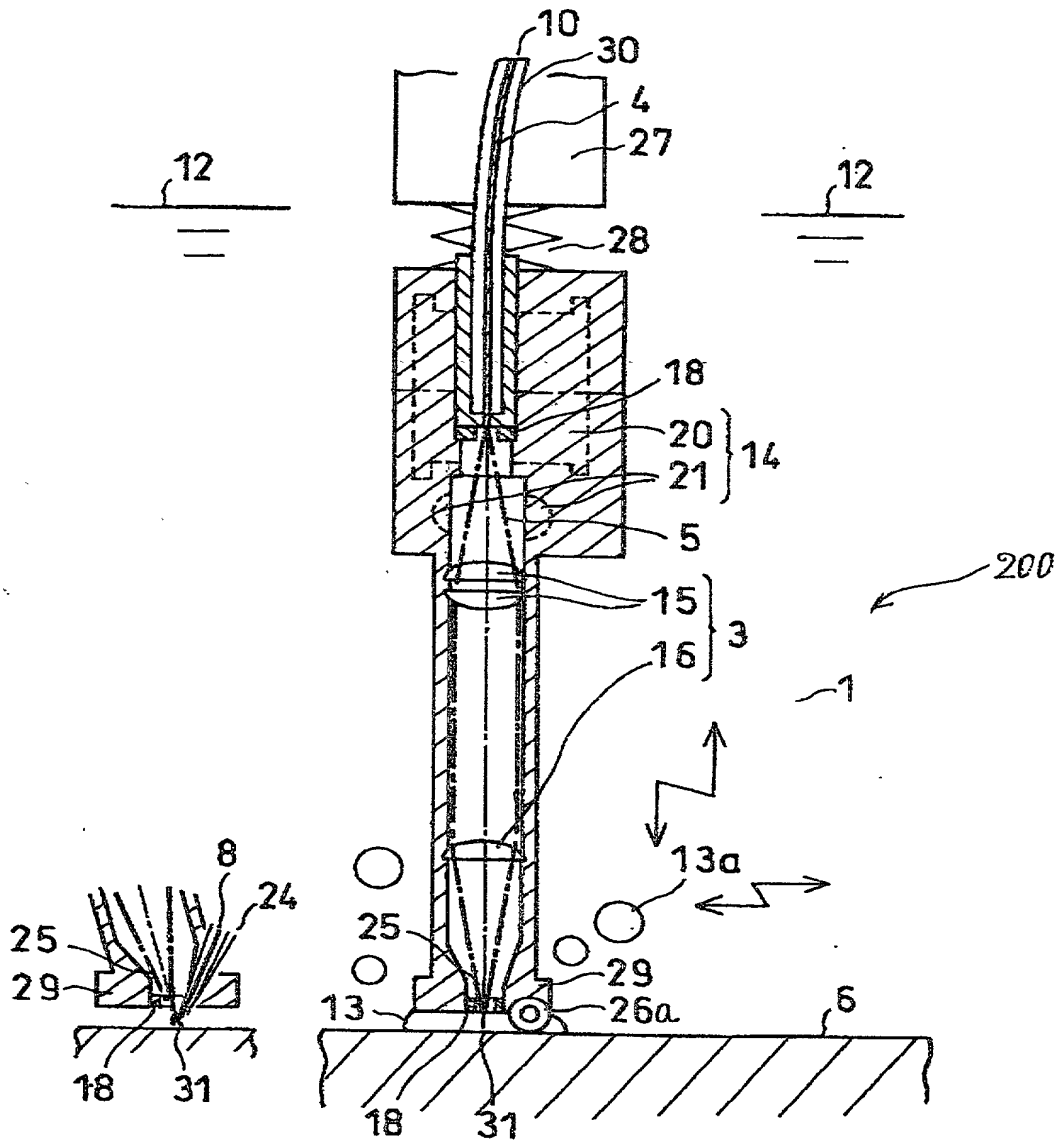


Fig. 7B

Fig. 7A

Fig. 8B

Fig. 8A